AMPHENOL TCS

TB-2072

VHDM® DAUGHTERCARD POWER MODULE REPLACEMENT PROCEDURE

Revision “D“

Specification Revision Status

Revision	SCR No.	Description	Initial	Date
“-“	27119	Initial Release	E. Ekstrom	3-8-99
“A”	31075	Revised Title Added New Paragraph 3.0 Renumbered Subsequent Paragraphs	C. Kowalczyk	6-6-00
“B”	40227	New Template, Added Trademark	K. Taber	10-16-02
“C”	S0081	Replaced template format	M.Lee	02-03-06
“D”	S0802	Updated copyright information	C Palmer	02-26-08

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1.0 SCOPE

1.1 This technical bulletin describes the procedure for VHDM daughtercard power module replacement.

2.0 TOOLS

2.1 Stiffener Removal Tool – Part No. 600-1875-000

2.2 Miniature Needle Nose Pliers

2.3 Small Press and Delrin Block

2.4 Pallet to Support PC Board (Not Shown)

2.5 One Piece Starrett Feeler Gauge Stock 0.004” Thick and Approximately 4” Long

Figure 1

3.0 SET-UP PROCEDURE FOR TOOLS

3.1 Prior to removing the stiffener, check to insure the stiffener removal tool is properly set for the connector to be repaired (daughtercard or right angle male). If the connector is a daughtercard, the pin block should be oriented as shown in Figure 2. The proper orientation for right angle male is shown in Figure 3. Proper orientation is achieved by removing the two flat head screws in the pin block, sliding it clear of the two locating pins, rotating the pin block 180º, sliding it back on the locating pins, and replacing the screws.

Figure 2

Figure 3

4.0 REMOVAL OF DAMAGED MODULE

4.1 The first step is to remove the stiffener as described in Paragraph 3.0 (see Figure 4).

4.2 The power module is comprised of two pieces of plastic, both need to be removed. Remove the front by grasping with pliers and pulling straight away from the connector (see Figure 5). The second piece or rear half can then be lifted away from the assembly (see Figure 6). With the insulator removed, the power blades can individually bent perpendicular to the PC board and pulled straight up to remove them (see Figure 7).

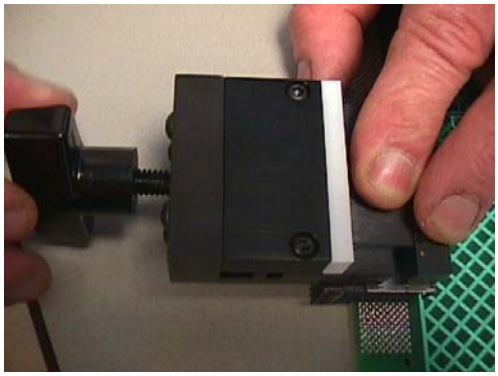

Figure 4

Figure 5

Figure 6

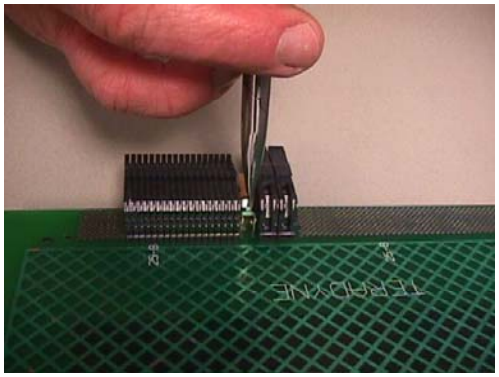

Figure 7

5.0 REPLACEMENT OF THE MODULE

5.1 The replacement power module assembly is placed in position and pre-seated in the plated through holes (see Figure 8).

5.2 The use of 0.004” thick feeler gauge stock is necessary only if there is a signal wafer to the right of the power module being replaced. If the shim is required, it should be inserted to a depth of 8mm minimum from the mating interface between the power module and the signal wafer to its right (see Figure 9). The purpose of the shim is to protect the plastic tabs on the signal wafer during the final seating process.

5.3 Place the board on a pallet or other support, place the Delrin block on top of the power module (s), and press until the module (s) is properly seated (same height as other components). Remove shim (if used) by pulling away from the connector.

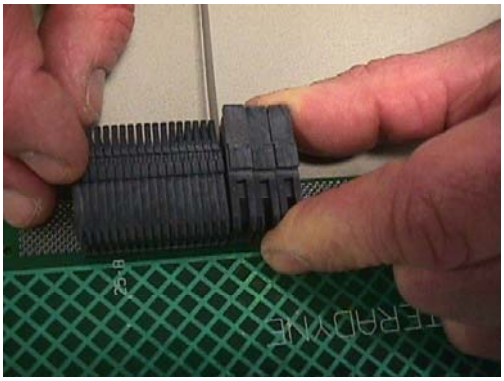

Figure 8

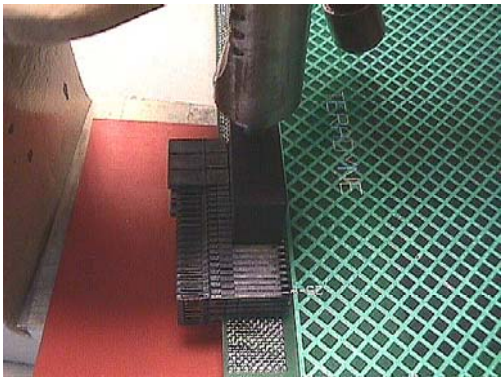

Figure 9

6.0 REPLACEMENT OF THE STIFFENER

6.1 The replacement of the stiffener is described in Steps 9 and 10 of TB-2043 using Tool No. 600-1875-000

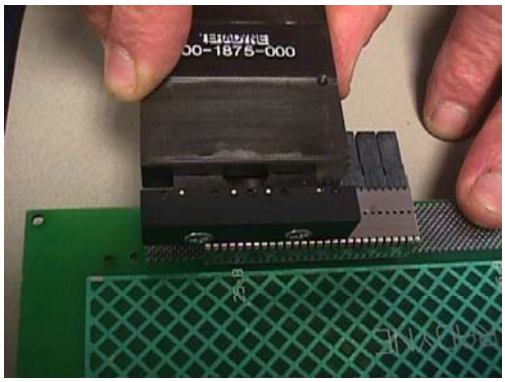

Figure 10